


MATERIAL DECLARATION SHEET



Material Number	CDDFN2-T3.3B			
Product Line	Semiconductor Products			
Compliance Date	2024/8/15			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.03570	Silicon	7440-21-3	100.00%	3.850%	3.850%
2	Lead Frame	Noble metal	0.41809	Copper	7440-50-8	95.28%	45.089%	47.323%
			0.01303	Nickel	7440-02-0	2.97%	1.406%	
			0.00281	Silicon	7440-21-3	0.64%	0.303%	
			0.00066	Magnesium	7439-95-4	0.15%	0.071%	
		Plating	0.00391	Nickel plating	7440-02-0	100.00%	0.421%	
			0.00022	Palladium plating	7440-05-3	100.00%	0.024%	
			0.00009	Gold plating	7440-57-5	100.00%	0.009%	
3	Epoxy	Polymer	0.00664	Silver	7440-22-4	83.00%	0.716%	0.863%

MATERIAL DECLARATION



			0.00082	2-Propionic acid, methyl ester reaction products with hydrolyzed formic acid-polydicyclopentadiene reaction product	Proprietary	10.20%	0.088%	
			0.00042	Amines, C36-alkylenedi-, maleated	682800-79-9	5.20%	0.045%	
			0.00010	2-Propenoic acid, 2-methyl-, 2-[[2,3,3a,4,7,7a(or 3a,4,5,6,7,7a)-hexahydro-4,7-methano-1H-indenyl]oxy]ethyl ester	68586-19-6	1.20%	0.010%	
			0.00002	2-(3,4-Epoxycyclohexyl)ethyltrimethoxy silane	3388-04-3	0.30%	0.003%	
			0.00001	2-Propenoic acid, 2-methyl, palladium (2+) salt	1947330-20-2	0.10%	0.001%	
4	Wire	Noble metal	0.00490	Aurum	7440-57-5	99.99%	0.528%	0.539%
			0.00010	Others	/	0.01%	0.011%	

MATERIAL DECLARATION



5	Mold Compound	Polymer	0.01319	Epoxy Resin A	Trade Secret	3.00%	1.423%	47.425%
			0.01319	Epoxy Resin B	Trade Secret	3.00%	1.423%	
			0.01319	Phenol Resin A	Trade Secret	3.00%	1.423%	
			0.01319	Phenol Resin B	Trade Secret	3.00%	1.423%	
			0.34077	Silica(Amorphous) A	60676-86-0	77.50%	36.753%	
			0.03078	Silica(Amorphous) B	7631-86-9	7.00%	3.320%	
			0.01319	Metal Hydroxide	Trade Secret	3.00%	1.423%	
			0.00220	Carbon Black	1333-86-4	0.50%	0.237%	
		Total weight	0.9272 mg					

This Document was updated on: 2024/8/15

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.